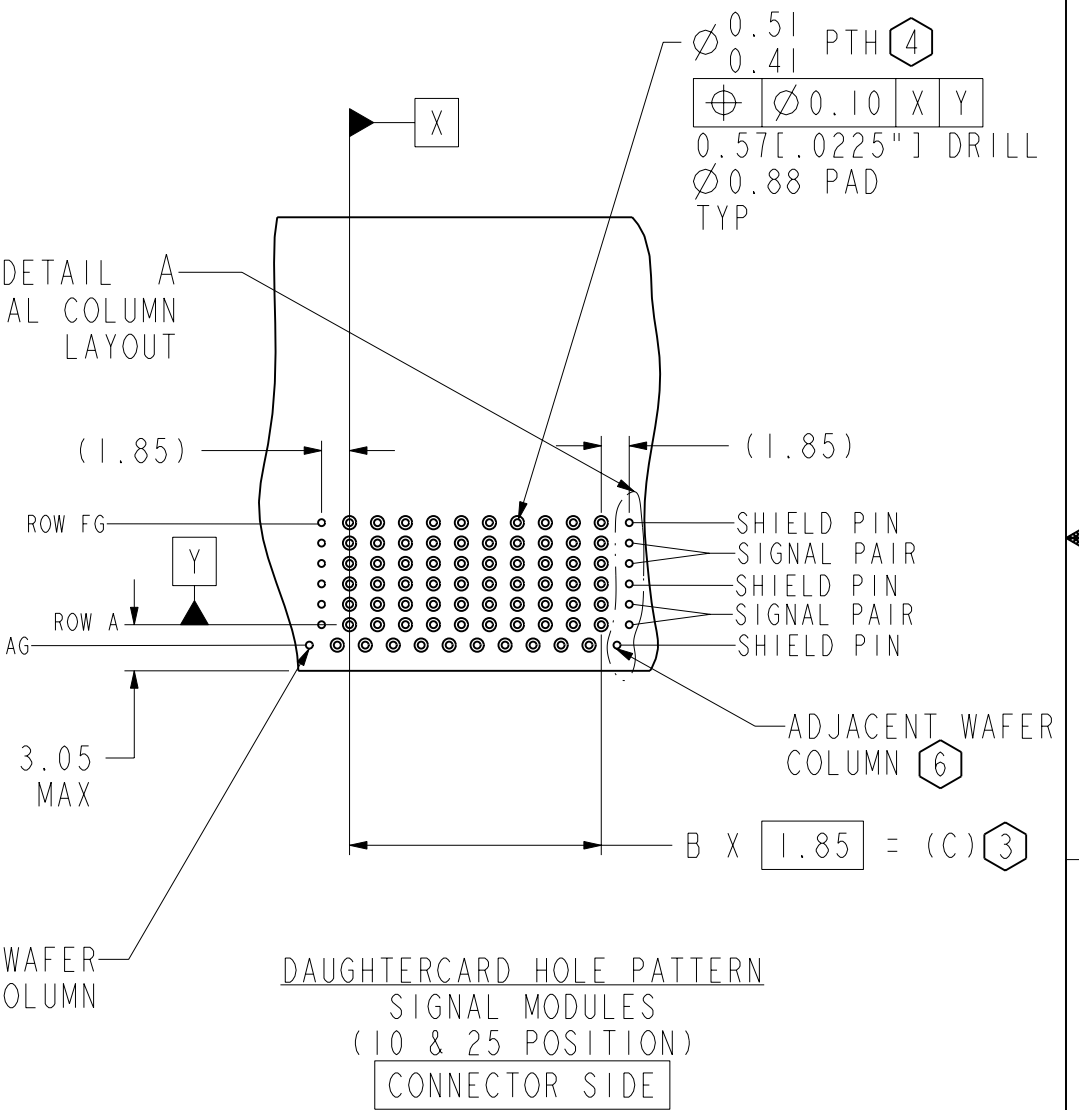
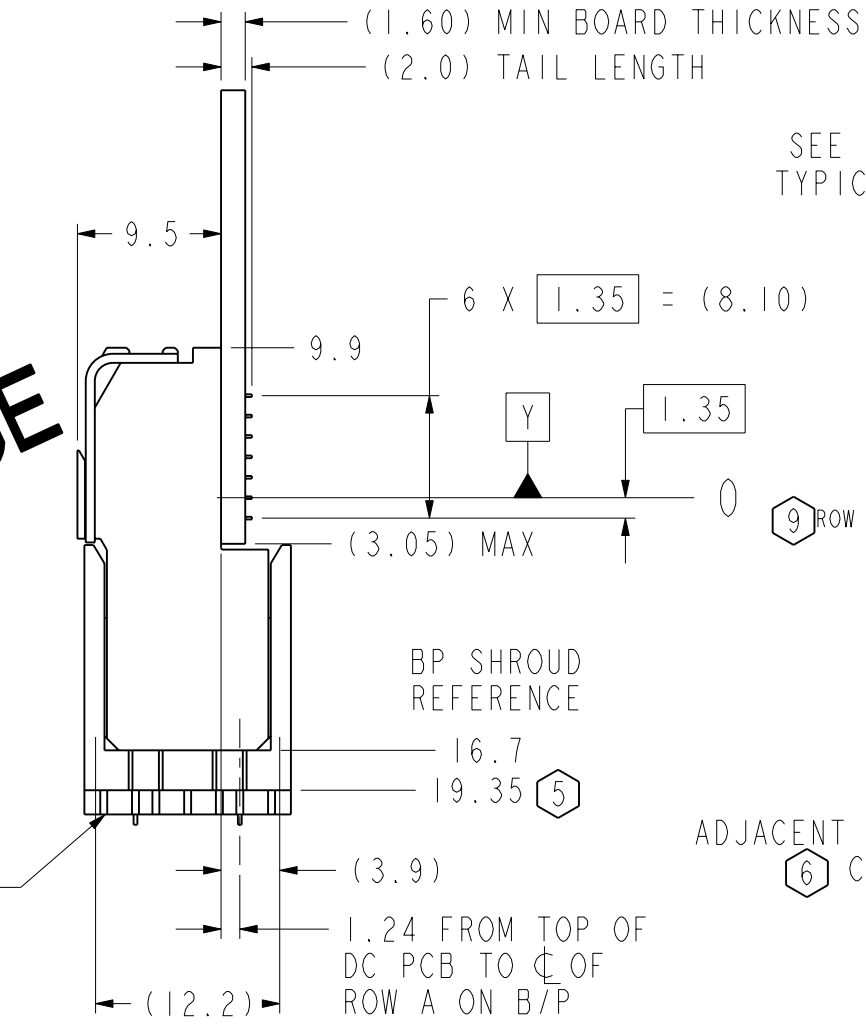
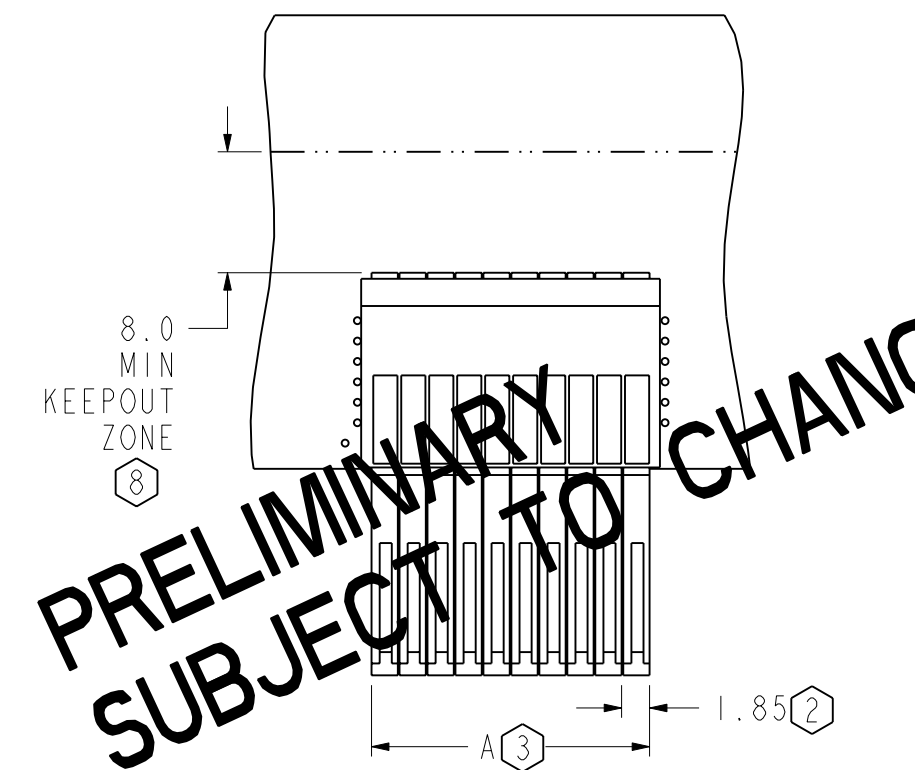


ZONE	REV	SCR NO.	DESCRIPTION	BY	DATE	APPROVED
	01		NEW RELEASE	R.C.	08/05/03	

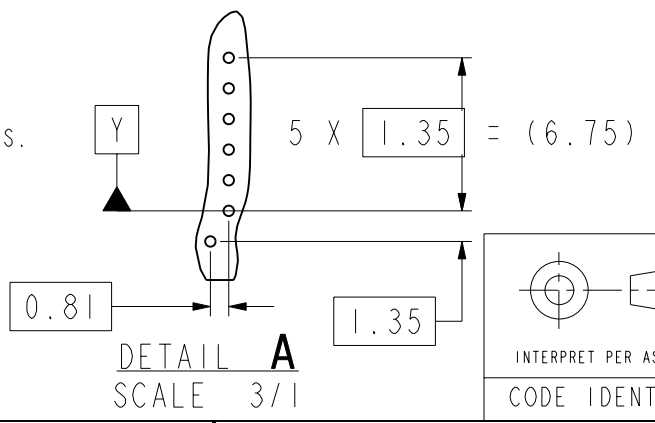
PART NUMBER	REV	DESCRIPTION
167-5101-735	01	30μ IN. GOLD MATING PLATING
167-5101-732	01	50μ IN. GOLD MATING PLATING

NUMBER OF WAFERS	A	B	C
10	18.50	9	16.65
25	46.25	24	44.40



- ⑨ GROUND ROWS ARE AG, C & FG. ALL OTHER ROWS ARE SIGNAL ROWS.
- ⑧ FOR CONNECTOR REPAIRABILITY, USE KEEP OUT ZONE.
- 7. REFER TO TB-2085 FOR GbX PRODUCT SPECIFICATIONS.
- ⑥ ADJACENT WAFER COLUMNS SHOWN FOR REFERENCE.
- ⑤ NOMINAL DIMENSION FOR FULLY SEATED CONNECTOR. EQUIVALENT TO 18.0 MM IN OTHER GbX SIZES.
- ④ STATED PAD SIZE MAY REQUIRE FILLETING. SEE TB-2090 FOR ROUTING GUIDELINES.
- ③ FOR WAFERS USED IN GROUPS OF 10 OR 25, SEE TABLE 2. REFER TO DESIGN GUIDELINES.
- ② USE 1.85mm NOMINAL FOR DAUGHTERCARD LAYOUT.

NOTES:  
1. INTENDED FOR LAYOUT PURPOSES ONLY.



TOLERANCES	DESIGN	01/22/03 R.CHIFFY
0,0	±0,25	
0,00	±0,13	
0,000	± -	
ANGLES	± 3°	

**TERADYNE**  
TERADYNE CONNECTION SYSTEMS, INC.  
44 SIMON STREET, NASHUA, N.H. 03060 (603) 879-3000

TITLE  
DAUGHTERCARD WAFER ASSEMBLY  
2 PAIR GbX

PART NO. SEE TABLE 1

DRAWING NO. C-167-5101-500

ProcASSEM S1-P1034-CU-OPEN-GEN  
P1034-CU-WAFER .dwg

SIZE B SCALE 1/1 SHEET 1 OF 1

UNLESS OTHERWISE SPECIFIED  
DIMENSIONS ARE IN MM

CUSTOMER USE  
DRAWING

INTERPRET PER ASME Y14.5M  
CODE IDENT 31413

DRW NO. C-167-5101-500  
SH 1  
REV 01